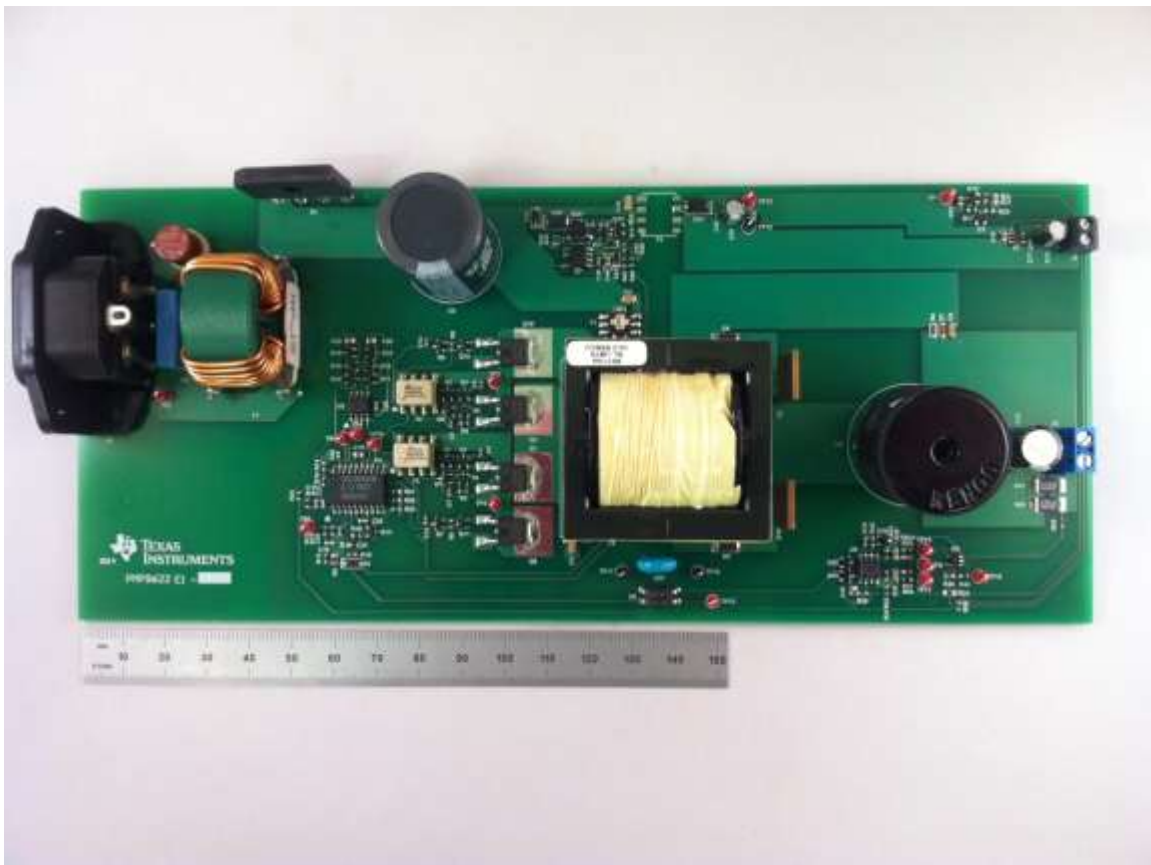


**1 Photo**



**2 EFFICIENCY**

Since measuring AC to DC efficiency tends to be not as accurate, DC to DC efficiency was also measured. The DC was applied after the ac bridge at various output currents and 150 v DC.

dc v in	I in	p in	v out	I out	p out	efficiency
150	0.635	95.25	43.6	2	87.2	91.54856
150	1.248	187.2	43.6	4	174.4	93.16239
150	1.866	279.9	43.6	6	261.6	93.46195
150	2.465	369.75	43.6	7.9	344.44	93.15483

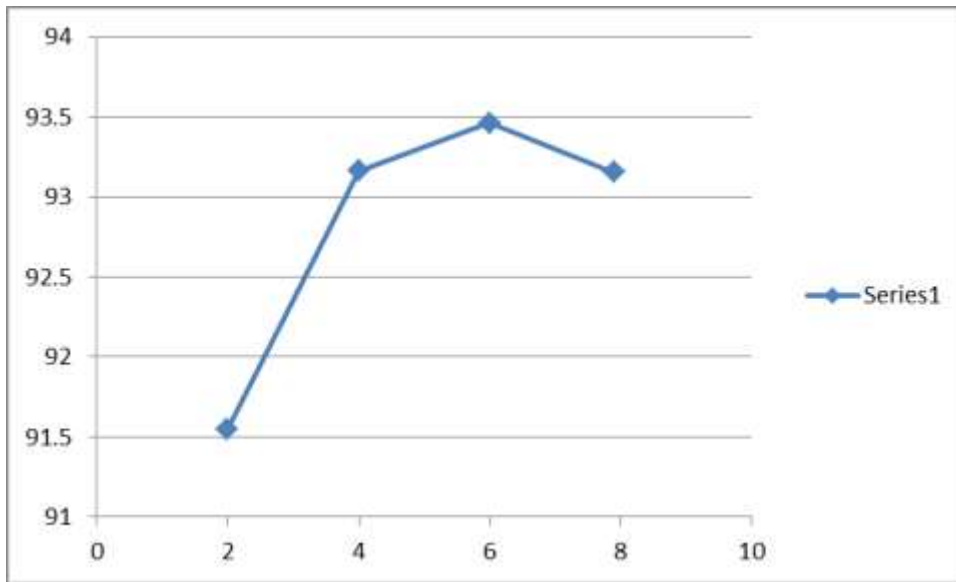
from AC meter

ac in						
120		99.62	43.6	2	87.2	87.53262
		194.02	43.6	4	174.4	89.88764
		289.7	43.6	6	261.6	90.30031
		372.7	43.6	7.9	344.44	92.41749
108		372.7	43.6	7.9	344.44	92.41749
132		372	43.6	7.9	344.44	92.5914

3/27/14

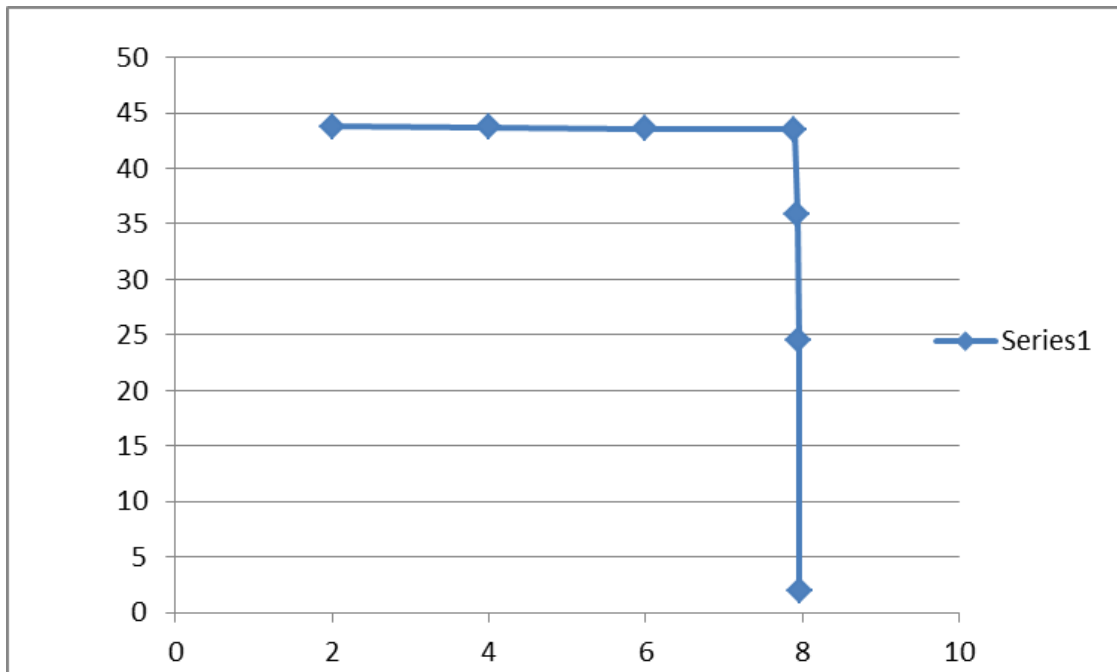
## PMP9622 Test Results

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Efficiency V.S. output current

### 3 Output load characteristics



#### Output current and voltage

The power supply is set up to be constant voltage-constant current.

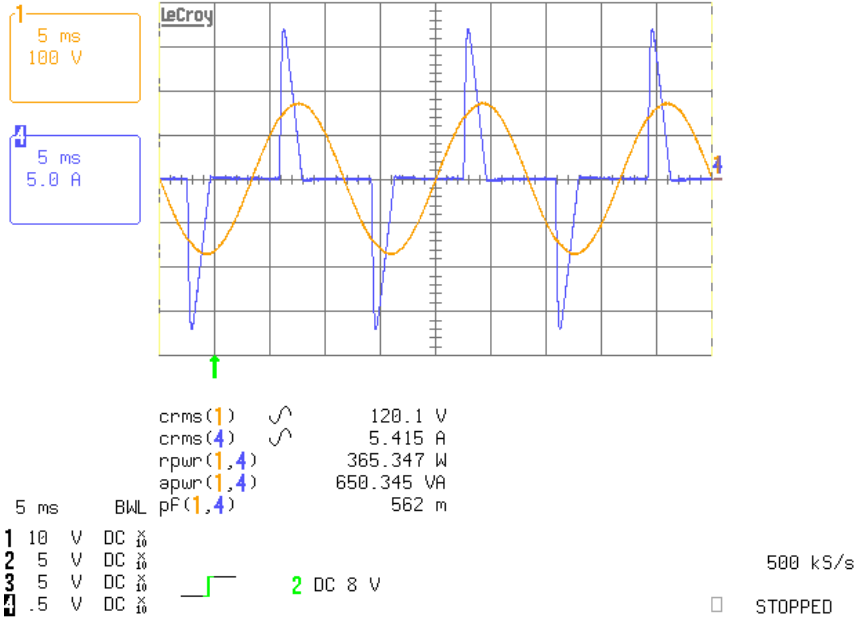
The voltage and current are set by fixed resistor values and could be set by micro-processor in the actual product.

3/27/14  
PMP9622 Test Results

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### 4 Input line at 7.8 amp load

26-Mar-14  
14:50:48



Blue is current, orange is 120Vac

## 5 Thermal image

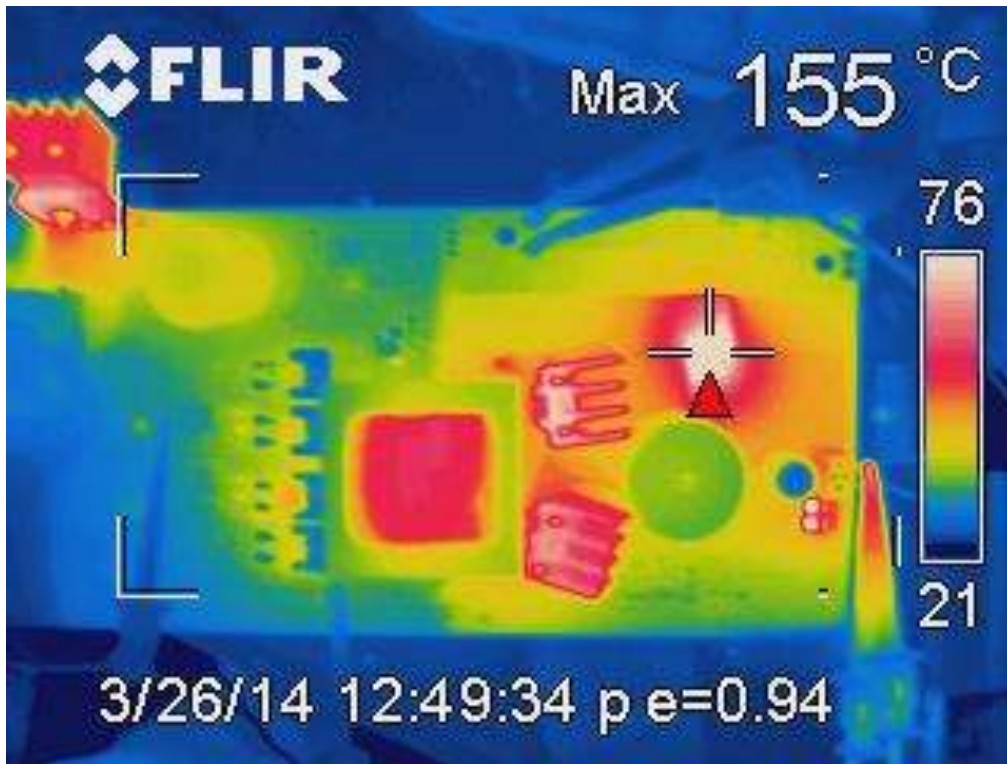
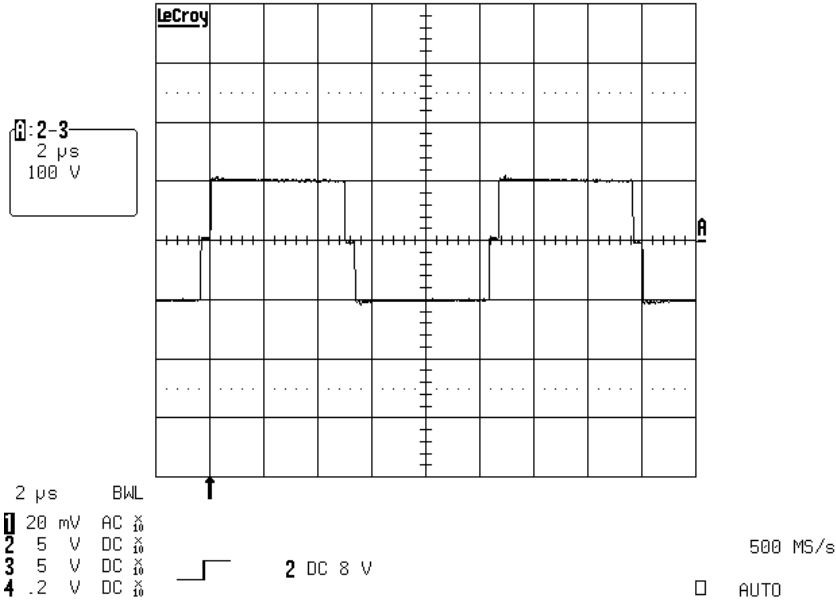


Image taken at full load in still air at 24 deg C. the hottest part on the board is are the snubber Rs and the diode bridge.

3/27/14  
PMP9622 Test Results

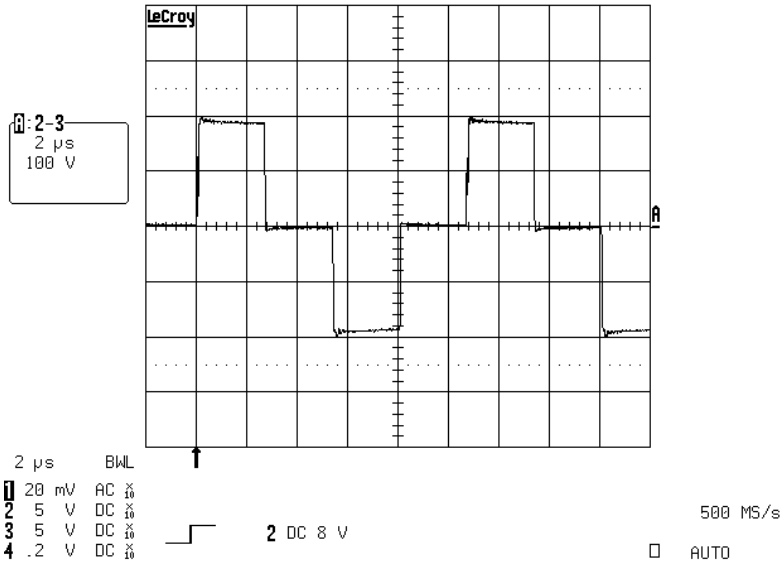
6 Dain wave forms. Voltage across the transformer primary

26-Mar-14  
13:17:21



At 7.7amp load and 100Vdc in

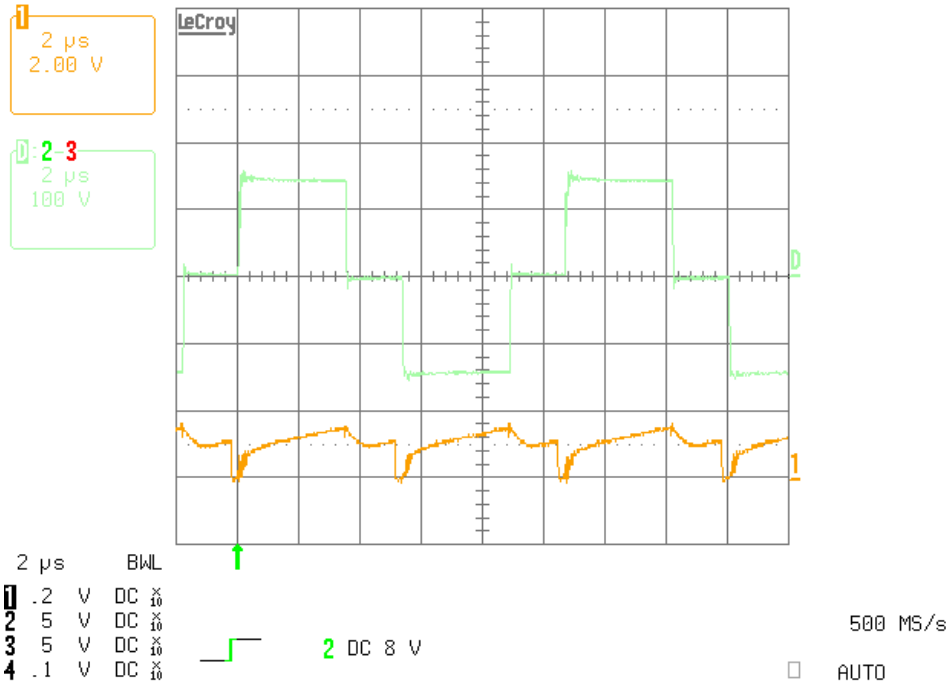
26-Mar-14 Reading Floppy Disk Drive  
13:16:18



At 7.7 amp load and 180Vdc in

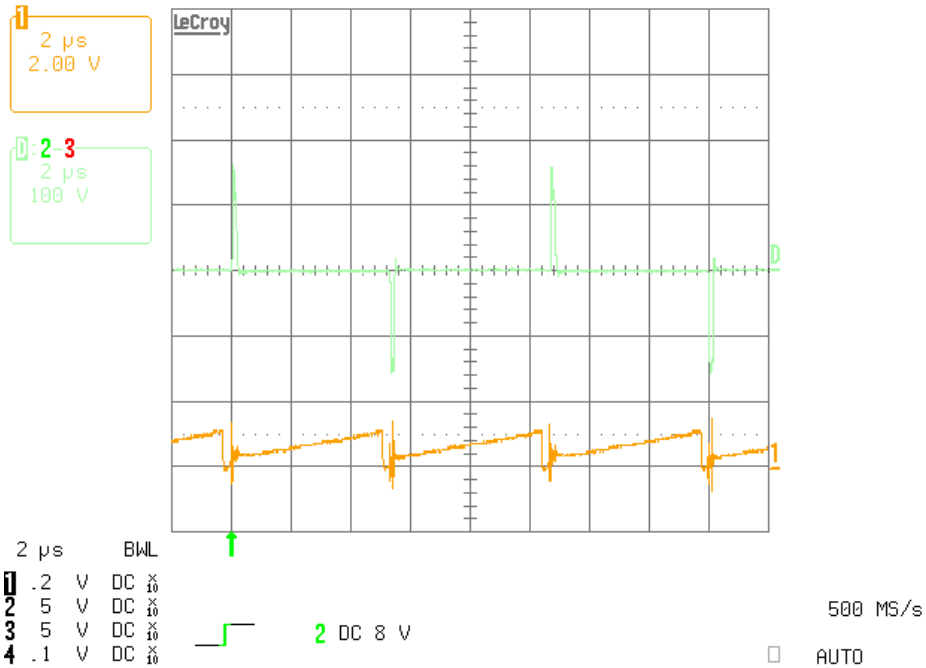
# 3/27/14 PMP9622 Test Results

26-Mar-14  
15:46:37



Voltage across the Tx and the current sense pin of the IC at full load

26-Mar-14  
15:47:21

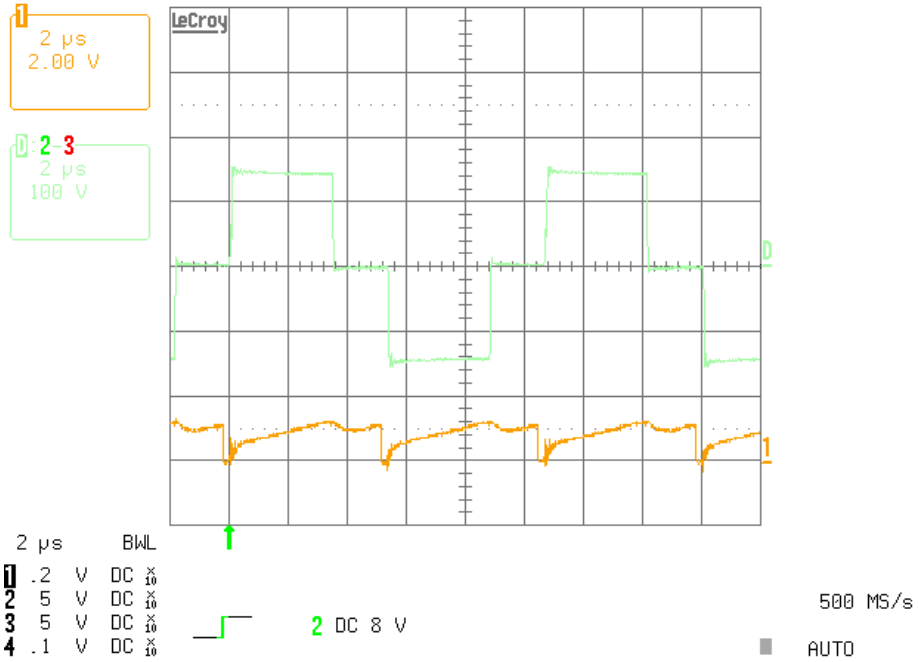


At no load



# 3/27/14 PMP9622 Test Results

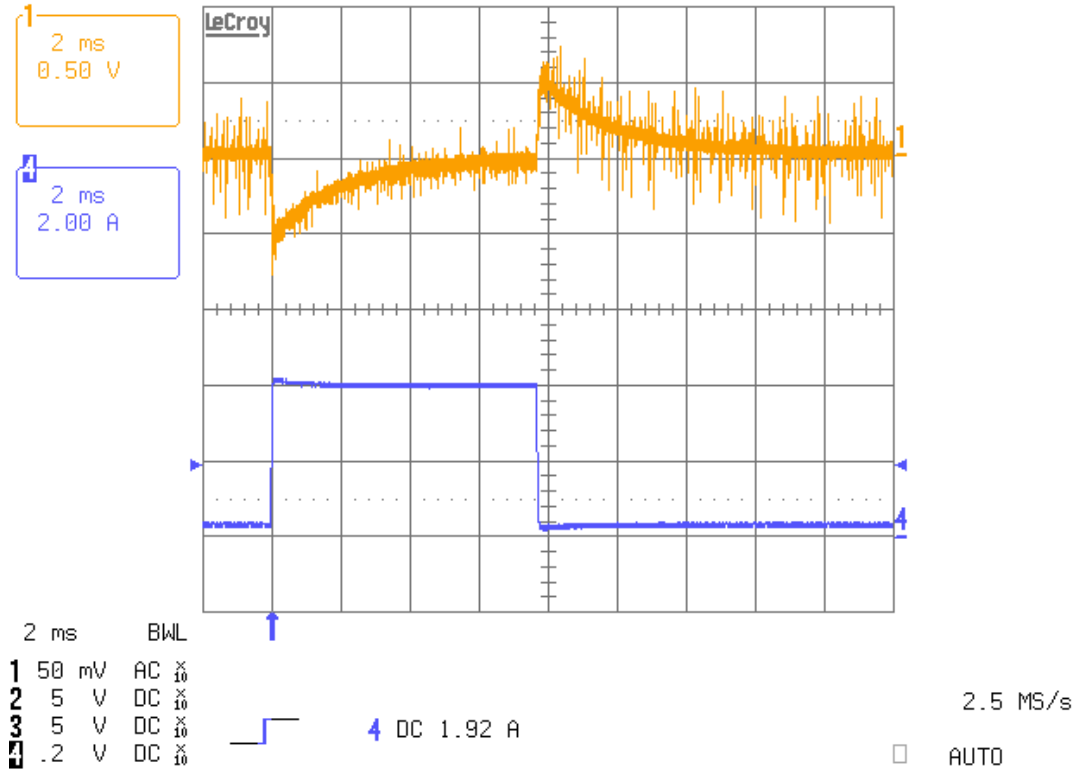
26-Mar-14  
15:47:37



At half load

## 7 Constant voltage mode load step response

26-Mar-14  
12:40:24

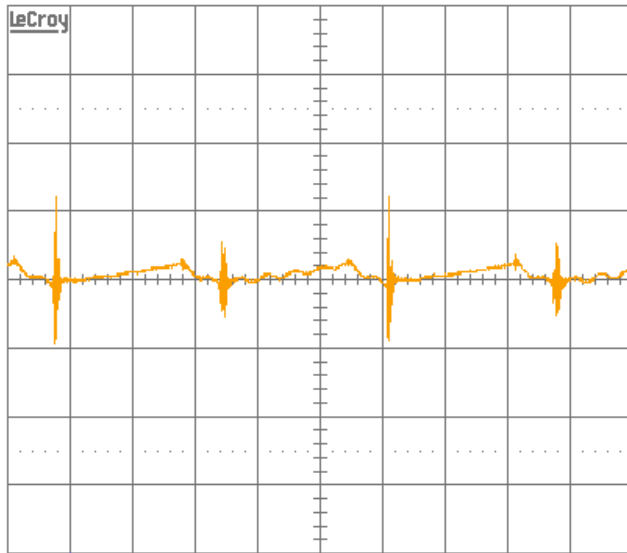


Blue is the load current step, orange is the output voltage response

## 8 Output ripple

26-Mar-14  
12:41:25

2  $\mu$ s  
200mV



2  $\mu$ s    BWL  
1 20 mV AC  $\times \frac{1}{10}$   
2 5 V DC  $\times \frac{1}{10}$   
3 5 V DC  $\times \frac{1}{10}$   
4 .2 V DC  $\times \frac{1}{10}$



4 DC 1.92 A

CHANNEL 1

Trace  
OFF  On

Coupling

ZOOM

FIND

Gain  
Fixed  
variable

Offsets in  
Volts  
Divisions

Grids  
Single Dual  
Quad Octal

500 MS/s

AUTO

At full load

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